

MECHANICAL CASE OUTLINE

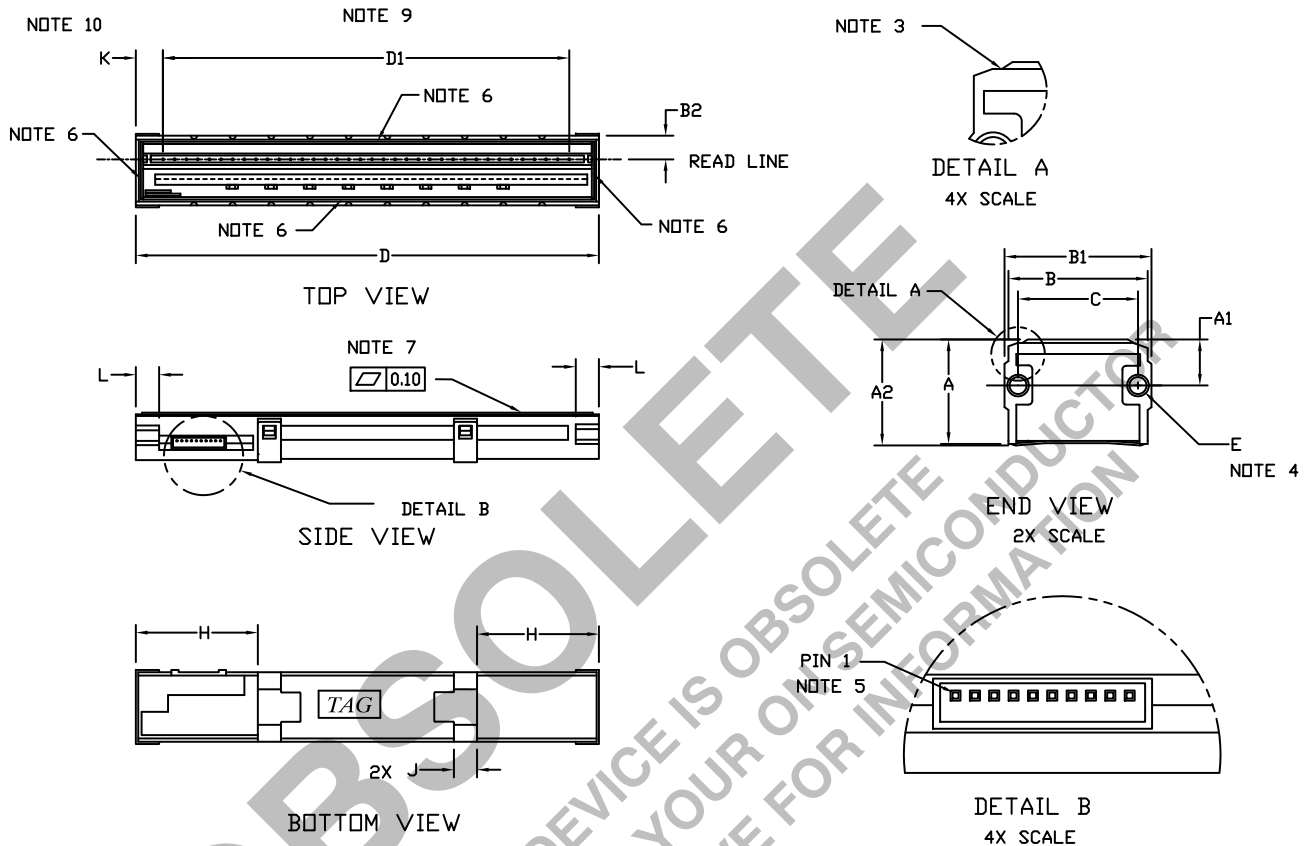
PACKAGE DIMENSIONS

ON Semiconductor®



IMAGE SENSOR MODULE CASE MODAF ISSUE A

DATE 17 DEC 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEADING EDGE OF THE APPROACH ANGLE ON THE GLASS IS LOWER THAN THE TOP OF THE HOUSING.
4. BORE DEPTH IS 6.0 WITH A 0.2 LEAD-IN CHAMFER.
5. PIN HEADER, MODEL NUMBER EBW-PK23-P010L2-3Z, 1X10 PIN, PITCH 1.25.
6. GLASS IS GLUED ON ALL 4 SIDES.
7. GLASS THICKNESS IS 1.85.
8. USE M2.3 SELF TAPPING SCREWS FOR MOUNTING. TORQUE SCREWS BETWEEN 1.80 KGF-CM AND 2.00 KGF-CM.
9. DIMENSION D1 DENOTES THE SCAN LENGTH.
10. DIMENSION K DENOTES THE POSITION OF THE FIRST PIXEL.

MILLIMETERS		
DIM	MIN	MAX
A	13.00	14.00
A1	6.70	7.70
A2	13.20	14.20
B	17.70	18.30
B1	18.70	19.30
B2	5.50	6.50
C	15.20	15.80
D	119.20	120.20
D1	104.00	REF
E	2.10	2.30
H	34.80	35.80
J	5.70	6.30
K	6.00	8.00
L	6.00	REF

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	IMAGE SENSOR MODULE MODAF	PAGE 1 OF 2

